



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

ATTY.'S DOCKET: 98 P7501 US 01

In re the application of:)
Ramachandran et al.) Group Art: 1746
Serial No.: 09/204,706) Examiner: A. Olsen
Filing Date: December 3, 1998)
Title: REMOVAL OF POST-RIE POLYMER) ON Al/Cu METAL LINE)

AMENDMENT UNDER 37 C.F.R. §1.115

Honorable Commissioner of Patents and Trademarks
Washington, D.C. 20231

Sir:

In reply to the Office Action mailed March 28, 2002,
which rejected the claims in the above-identified patent
application, applicants respectfully request reconsideration,
based upon the amendments hereinafter set forth.

IN THE CLAIMS:

13. (4th Amended) In a metal etch tool for removing post-
RIE polymer rails formed on a Al/Cu metal line of a
semiconductor structure, the improvement comprising:

I an integrated metal etch tool interfaceable with
[comprising therein]:

- a) strip chamber means for water only plasma to strip
photo-resist of a semiconductor composite structure subsequent
to a RIE to limit thickness of sidewall polymer rails;
- b) vacuum chamber means to chemically modify sidewall

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